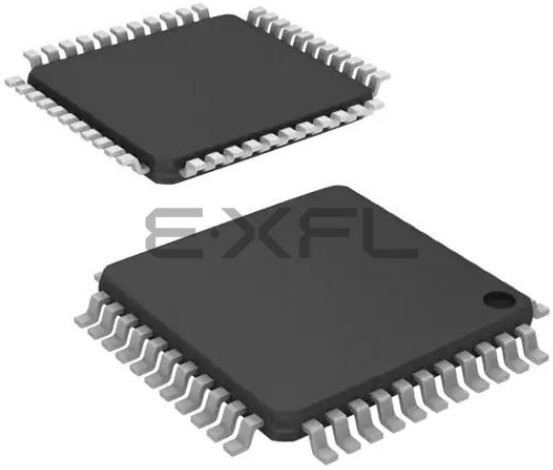
Microchip Technology - PIC24HJ128GP204-I/PT Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj128gp204-i-pt

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Programming"** (DS70191) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows the PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 devices to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGEC1/PGED1, PGEC2/PGED2 or PGEC3/PGED3), and three other lines for power (VDD), ground (VSS) and Master Clear (MCLR). This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (table read) and TBLWT (table write) instructions. With RTSP, the user application can write program memory data either in blocks or 'rows' of 64 instructions (192 bytes) at a time or a single program memory word, and erase program memory in blocks or 'pages' of 512 instructions (1536 bytes) at a time.

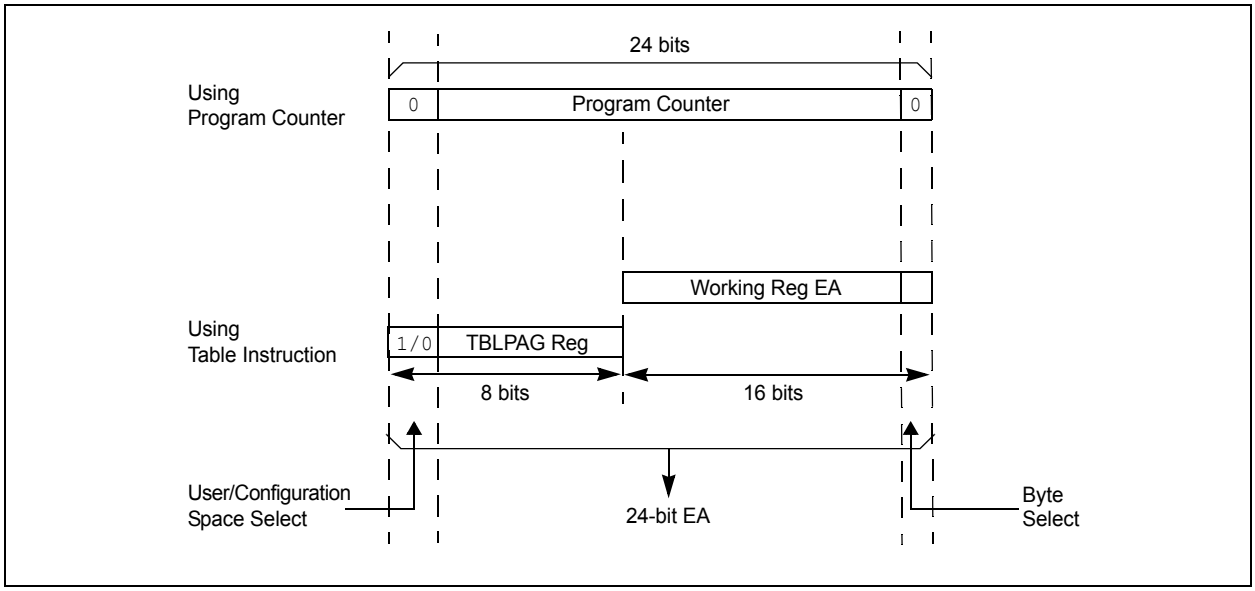
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table read and table write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits <7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits <15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits <23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



6.0 RESETS

Note 1: This data sheet summarizes the features of the PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Reset"** (DS70192) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Reset module combines all reset sources and controls the device Master Reset Signal, SYSRST. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- MCLR: Master Clear Pin Reset
- SWR: RESET Instruction
- WDTO: Watchdog Timer Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
  - Illegal Opcode Reset
  - Uninitialized W Register Reset
  - Security Reset

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of reset will make the SYSRST signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state and some are unaffected.

Note: Refer to the specific peripheral section or **Section 3.0 "CPU"** of this manual for register Reset states.

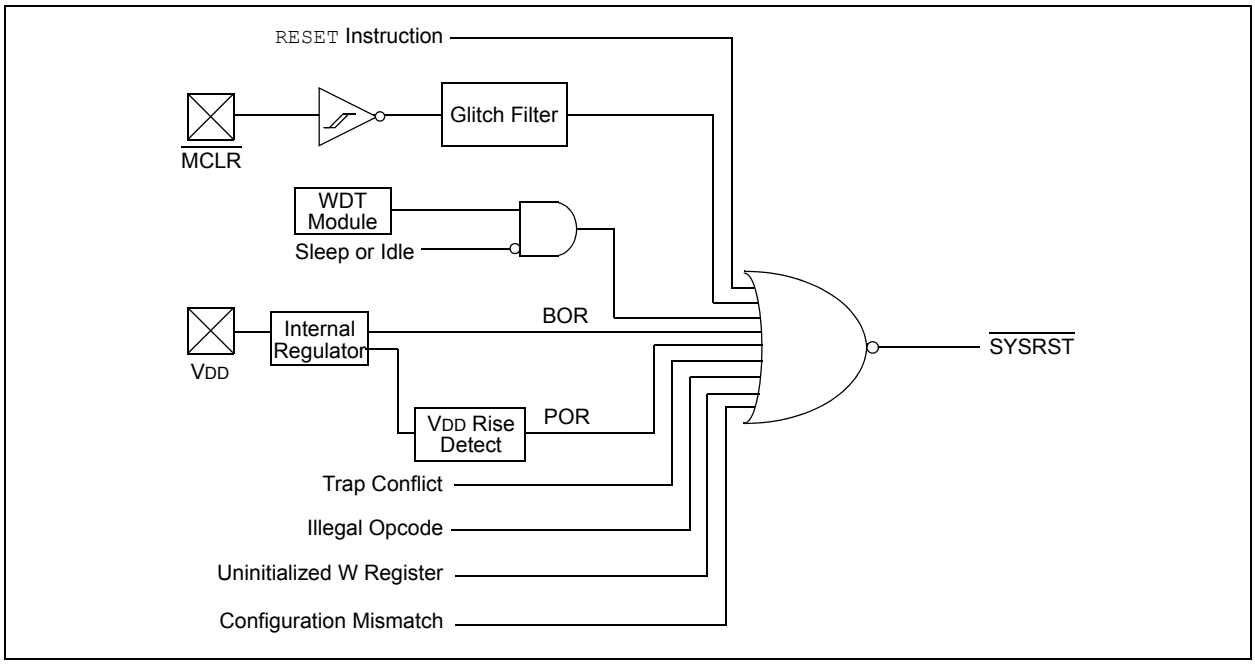
All types of device Reset sets a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

A POR clears all the bits, except for the POR bit (RCON<0>), that are set. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this manual.

Note: The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset is meaningful.

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM



6.1 Reset Resources

Many useful resources related to Resets are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en534555

6.1.1 KEY RESOURCES

- **Section 8. "Resets"** (DS70192)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

6.2 Reset Control Registers

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1)

R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	—	—	—	—	CM	VREGS
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR	SWR	SWDTEN(2)	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or uninitialized W Reset has not occurred

bit 13-10 **Unimplemented:** Read as '0'

bit 9 **CM:** Configuration Mismatch Flag bit
1 = A configuration mismatch Reset has occurred.
0 = A configuration mismatch Reset has NOT occurred

bit 8 **VREGS:** Voltage Regulator Standby During Sleep bit
1 = Voltage regulator is active during Sleep
0 = Voltage regulator goes into Standby mode during Sleep

bit 7 **EXTR:** External Reset ($\overline{MCLR}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(2)
1 = WDT is enabled
0 = WDT is disabled

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

bit 3 **SLEEP:** Wake-up from Sleep Flag bit
1 = Device has been in Sleep mode
0 = Device has not been in Sleep mode

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

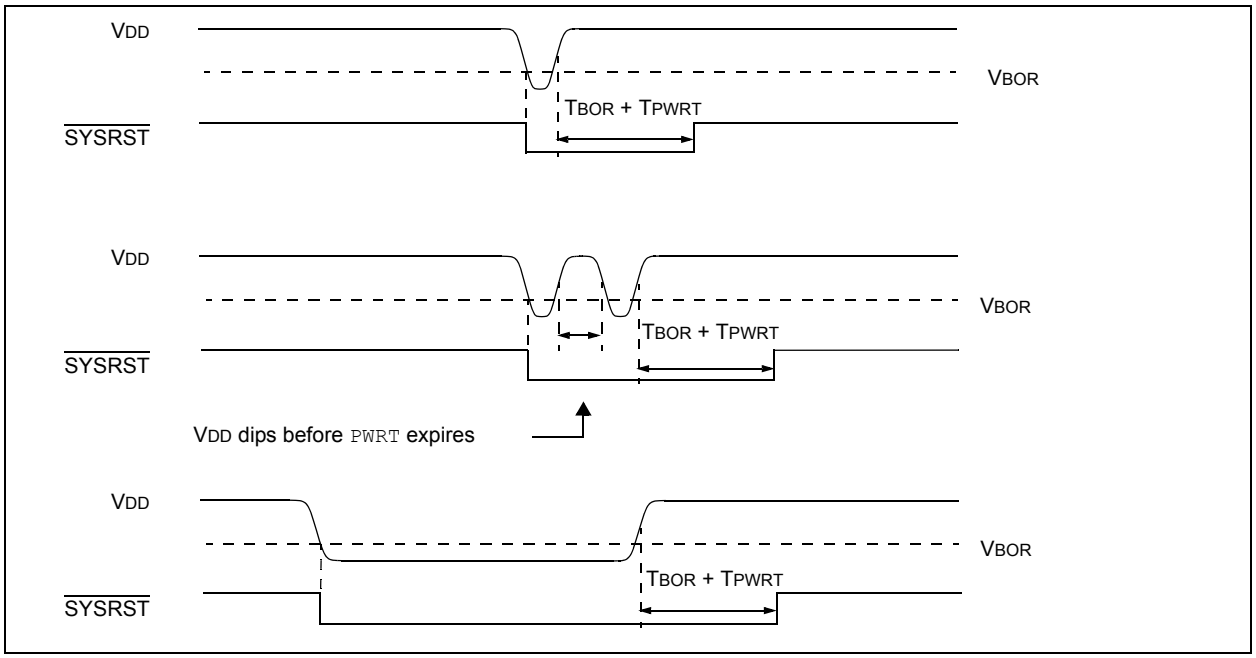
bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

FIGURE 6-3: BROWN-OUT SITUATIONS



6.5 External Reset (EXTR)

The external Reset is generated by driving the $\overline{MCLR}$ pin low. The $\overline{MCLR}$ pin is a Schmitt trigger input with an additional glitch filter. Reset pulses that are longer than the minimum pulse width will generate a Reset. Refer to **Section 28.0 "Electrical Characteristics"** for minimum pulse width specifications. The External Reset ($\overline{MCLR}$) Pin (EXTR) bit in the Reset Control (RCON) register is set to indicate the $\overline{MCLR}$ Reset.

6.5.1 EXTERNAL SUPERVISORY CIRCUIT

Many systems have external supervisory circuits that generate reset signals to reset multiple devices in the system. This external Reset signal can be directly connected to the $\overline{MCLR}$ pin to reset the device when the rest of system is Reset.

6.5.2 INTERNAL SUPERVISORY CIRCUIT

When using the internal power supervisory circuit to reset the device, the external reset pin ($\overline{MCLR}$) should be tied directly or resistively to VDD. In this case, the $\overline{MCLR}$ pin will not be used to generate a Reset. The external reset pin ($\overline{MCLR}$) does not have an internal pull-up and must not be left unconnected.

6.6 Software RESET Instruction (SWR)

Whenever the RESET instruction is executed, the device will assert $\overline{SYSRST}$, placing the device in a special Reset state. This Reset state will not re-initialize the clock. The clock source in effect prior to the RESET instruction will remain. $\overline{SYSRST}$ is released at the next instruction cycle, and the reset vector fetch will commence.

The Software Reset (Instruction) Flag bit (SWR) in the Reset Control register (RCON<6>) is set to indicate the software Reset.

6.7 Watchdog Time-out Reset (WDTO)

Whenever a Watchdog time-out occurs, the device will asynchronously assert $\overline{SYSRST}$. The clock source will remain unchanged. A WDT time-out during Sleep or Idle mode will wake-up the processor, but will not reset the processor.

The Watchdog Timer Time-out Flag bit (WDTO) in the Reset Control register (RCON<4>) is set to indicate the Watchdog Reset. Refer to **Section 25.4 "Watchdog Timer (WDT)"** for more information on Watchdog Reset.

6.8 Trap Conflict Reset

If a lower-priority hard trap occurs while a higher-priority trap is being processed, a hard trap conflict Reset occurs. The hard traps include exceptions of priority level 13 through level 15, inclusive. The address error (level 13) and oscillator error (level 14) traps fall into this category.

The Trap Reset Flag bit (TRAPR) in the Reset Control register (RCON<15>) is set to indicate the Trap Conflict Reset. Refer to **Section 7.0 "Interrupt Controller"** for more information on trap conflict Resets.

REGISTER 7-18: IPC3: INTERRUPT PRIORITY CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	DMA1IP<2:0>		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	AD1IP<2:0>			—	U1TXIP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10-8 **DMA1IP<2:0>:** DMA Channel 1 Data Transfer Complete Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **AD1IP<2:0>:** ADC1 Conversion Complete Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **U1TXIP<2:0>:** UART1 Transmitter Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 11-23: RPOR8: PERIPHERAL PIN SELECT OUTPUT REGISTERS 8(1)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP17R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP16R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **RP17R<4:0>:** Peripheral Output Function is Assigned to RP17 Output Pin bits (see Table 11-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RP16R<4:0>:** Peripheral Output Function is Assigned to RP16 Output Pin bits (see Table 11-2 for peripheral function numbers)

Note 1: This register is implemented in 44-pin devices only.

REGISTER 11-24: RPOR9: PERIPHERAL PIN SELECT OUTPUT REGISTERS 9(1)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP19R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	RP18R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **RP19R<4:0>:** Peripheral Output Function is Assigned to RP19 Output Pin bits (see Table 11-2 for peripheral function numbers)

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **RP18R<4:0>:** Peripheral Output Function is Assigned to RP18 Output Pin bits (see Table 11-2 for peripheral function numbers)

Note 1: This register is implemented in 44-pin devices only.

15.3 Output Compare Control Registers

REGISTER 15-1: OCxCON: OUTPUT COMPAREx CONTROL REGISTER (x = 1, 2, 3 OR 4)

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0 HC	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	OCFLT	OCTSEL	OCM<2:0>		
bit 7							bit 0

Legend:	HC = Cleared in Hardware	HS = Set in Hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Stop Output Compare in Idle Mode Control bit
1 = Output Compare x halts in CPU Idle mode
0 = Output Compare x continues to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as '0'

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred
(This bit is only used when OCM<2:0> = 111)

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for Compare x
0 = Timer2 is the clock source for Compare x

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx, Fault pin enabled
110 = PWM mode on OCx, Fault pin disabled
101 = Initialize OCx pin low, generate continuous output pulses on OCx pin
100 = Initialize OCx pin low, generate single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initialize OCx pin high, compare event forces OCx pin low
001 = Initialize OCx pin low, compare event forces OCx pin high
000 = Output compare channel is disabled

REGISTER 18-1: UxMODE: UARTx MODE REGISTER (CONTINUED)

bit 4 **URXINV:** Receive Polarity Inversion bit
1 = UxRX Idle state is '0'
0 = UxRX Idle state is '1'

bit 3 **BRGH:** High Baud Rate Enable bit
1 = BRG generates 4 clocks per bit period (4x baud clock, High-Speed mode)
0 = BRG generates 16 clocks per bit period (16x baud clock, Standard mode)

bit 2-1 **PDSEL<1:0>:** Parity and Data Selection bits
11 = 9-bit data, no parity
10 = 8-bit data, odd parity
01 = 8-bit data, even parity
00 = 8-bit data, no parity

bit 0 **STSEL:** Stop Bit Selection bit
1 = Two Stop bits
0 = One Stop bit

Note 1: Refer to **Section 17. "UART"** (DS70232) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for receive or transmit operation.

2: This feature is only available for the 16x BRG mode (BRGH = 0).

REGISTER 19-10: CiCFG2: ECAN™ BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH<2:0>		
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **WAKFIL:** Select CAN bus Line Filter for Wake-up bit
1 = Use CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as '0'

bit 10-8 **SEG2PH<2:0>:** Phase Segment 2 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PH bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Segment 1 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

20.0 10-BIT/12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC1)

Note 1: This data sheet summarizes the features of the PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 devices have up to 13 ADC input channels.

The AD12B bit (AD1CON1<10>) allows each of the ADC modules to be configured by the user as either a 10-bit, 4-sample/hold ADC (default configuration) or a 12-bit, 1-sample/hold ADC.

Note: The ADC module needs to be disabled before modifying the AD12B bit.

20.1 Key Features

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 1.1 Msps
- Up to 13 analog input pins
- External voltage reference input pins
- Simultaneous sampling of up to four analog input pins
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Selectable Buffer Fill modes
- Operation during CPU Sleep and Idle modes

The 12-bit ADC configuration supports all the above features, except:

- In the 12-bit configuration, conversion speeds of up to 500 ksps are supported
- There is only one sample/hold amplifier in the 12-bit configuration, so simultaneous sampling of multiple channels is not supported.

Depending on the particular device pinout, the ADC can have up to 13 analog input pins, designated AN0 through AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs can be shared with other analog input pins. The actual number of analog input pins and external voltage reference input configuration depends on the specific device.

Block diagrams of the ADC module are shown in Figure 20-1 and Figure 20-2.

20.2 ADC Initialization

The following configuration steps should be performed.

1. Configure the ADC module:
   a) Select port pins as analog inputs (AD1PCFGH<15:0> or AD1PCFGL<15:0>)
   b) Select voltage reference source to match expected range on analog inputs (AD1CON2<15:13>)
   c) Select the analog conversion clock to match desired data rate with processor clock (AD1CON3<7:0>)
   d) Determine how many S/H channels are used (AD1CON2<9:8> and AD1PCFGH<15:0> or AD1PCFGL<15:0>)
   e) Select the appropriate sample/conversion sequence (AD1CON1<7:5> and AD1CON3<12:8>)
   f) Select how conversion results are presented in the buffer (AD1CON1<9:8>)
   g) Turn on ADC module (AD1CON1<15>)
2. Configure ADC interrupt (if required):
   a) Clear the AD1IF bit
   b) Select ADC interrupt priority

20.3 ADC and DMA

If more than one conversion result needs to be buffered before triggering an interrupt, DMA data transfers can be used. ADC1 can trigger a DMA data transfer. If ADC1 is selected as the DMA IRQ source, a DMA transfer occurs when the AD1IF bit gets set as a result of an ADC1 sample conversion sequence.

The SMPI<3:0> bits (AD1CON2<5:2>) are used to select how often the DMA RAM buffer pointer is incremented.

The ADDMABM bit (AD1CON1<12>) determines how the conversion results are filled in the DMA RAM buffer area being used for ADC. If this bit is set, DMA buffers are written in the order of conversion. The module provides an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer. If the ADDMABM bit is cleared, then DMA buffers are written in Scatter/Gather mode. The module provides a scatter/gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer.

REGISTER 22-3: ALCFGRPT: ALARM CONFIGURATION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ALRMEN	CHIME	AMASK<3:0>				ALRMPTR<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ARPT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ALRMEN:** Alarm Enable bit
1 = Alarm is enabled (cleared automatically after an alarm event whenever ARPT<7:0> = 0x00 and CHIME = 0)
0 = Alarm is disabled

bit 14 **CHIME:** Chime Enable bit
1 = Chime is enabled; ARPT<7:0> bits are allowed to roll over from 0x00 to 0xFF
0 = Chime is disabled; ARPT<7:0> bits stop once they reach 0x00

bit 13-10 **AMASK<3:0>:** Alarm Mask Configuration bits
11xx = Reserved – do not use
101x = Reserved – do not use
1001 = Once a year (except when configured for February 29th, once every 4 years)
1000 = Once a month
0111 = Once a week
0110 = Once a day
0101 = Every hour
0100 = Every 10 minutes
0011 = Every minute
0010 = Every 10 seconds
0001 = Every second
0000 = Every half second

bit 9-8 **ALRMPTR<1:0>:** Alarm Value Register Window Pointer bits
Points to the corresponding Alarm Value registers when reading ALRMVALH and ALRMVALL registers; the ALRMPTR<1:0> value decrements on every read or write of ALRMVALH until it reaches '00'.
ALRMVAL<15:8>:
11 = Unimplemented
10 = ALRMMNTH
01 = ALRMWD
00 = ALRMMIN
ALRMVAL<7:0>:
11 = Unimplemented
10 = ALRMDAY
01 = ALRMHR
00 = ALRMSEC

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits
11111111 = Alarm will repeat 255 more times
•
•
•
00000000 = Alarm will not repeat
The counter decrements on any alarm event. The counter is prevented from rolling over from 0x00 to 0xFF unless CHIME = 1.

TABLE 28-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
Operating Voltage							
DC10	**Supply Voltage**						
	VDD		3.0	—	3.6	V	Industrial and Extended
DC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	—	VSS	V	—
DC17	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.03	—	—	V/ms	0-3.0V in 0.1s

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: This is the limit to which VDD can be lowered without losing RAM data.

TABLE 28-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(5,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, and RB14
DI60b	IICH	**Input High Injection Current**	0	—	+5(6,7,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, RB14, and digital 5V-tolerant designated pins
DI60c	∑IICT	**Total Input Injection Current (sum of all I/O and control pins)**	-20(9)	—	+20(9)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑IICT

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **"Pin Diagrams"** for the 5V tolerant I/O pins.

5: VIL source < (VSS – 0.3). Characterized but not tested.

6: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 28-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min(1)**	**Typ**	**Max(1)**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low	2.40	—	2.55	V	VDD

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

TABLE 28-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130a	EP	Cell Endurance	10,000	—	—	E/W	-40° C to +125° C
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D132B	VPEW	VDD for Self-Timed Write	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
D136a	TRW	Row Write Time	1.32	—	1.74	ms	TRW = 11064 FRC cycles, TA = +85°C, See **Note 2**
D136b	TRW	Row Write Time	1.28	—	1.79	ms	TRW = 11064 FRC cycles, TA = +125°C, See **Note 2**
D137a	TPE	Page Erase Time	20.1	—	26.5	ms	TPE = 168517 FRC cycles, TA = +85°C, See **Note 2**
D137b	TPE	Page Erase Time	19.5	—	27.3	ms	TPE = 168517 FRC cycles, TA = +125°C, See **Note 2**
D138a	TWW	Word Write Cycle Time	42.3	—	55.9	µs	TWW = 355 FRC cycles, TA = +85°C, See **Note 2**
D138b	TWW	Word Write Cycle Time	41.1	—	57.6	µs	TWW = 355 FRC cycles, TA = +125°C, See **Note 2**

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

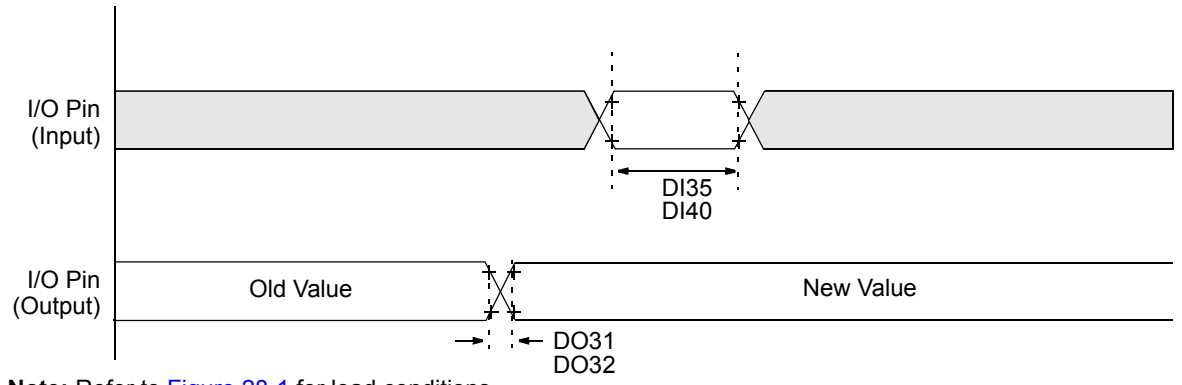
2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `b'011111` (for Min), TUN<5:0> = `b'100000` (for Max). This parameter depends on the FRC accuracy (see Table 28-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). For complete details on calculating the Minimum and Maximum time see **Section 5.3 "Programming Operations"**.

TABLE 28-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

Standard Operating Conditions (unless otherwise stated): Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
—	CEFC	External Filter Capacitor Value(1)	4.7	10	—	µF	Capacitor must be low series resistance (< 5 Ohms)

Note 1: Typical VCAP voltage = 2.5V when VDD ≥ VDDMIN.

FIGURE 28-3: CLKO AND I/O TIMING CHARACTERISTICS



Note: Refer to Figure 28-1 for load conditions.

TABLE 28-20: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	—
DO32	TIOF	Port Output Fall Time	—	10	25	ns	—
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	—
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	—

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

TABLE 28-34: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCK Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓to SCKx ↑ or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(4)	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 28-21: ECAN™ MODULE I/O TIMING CHARACTERISTICS

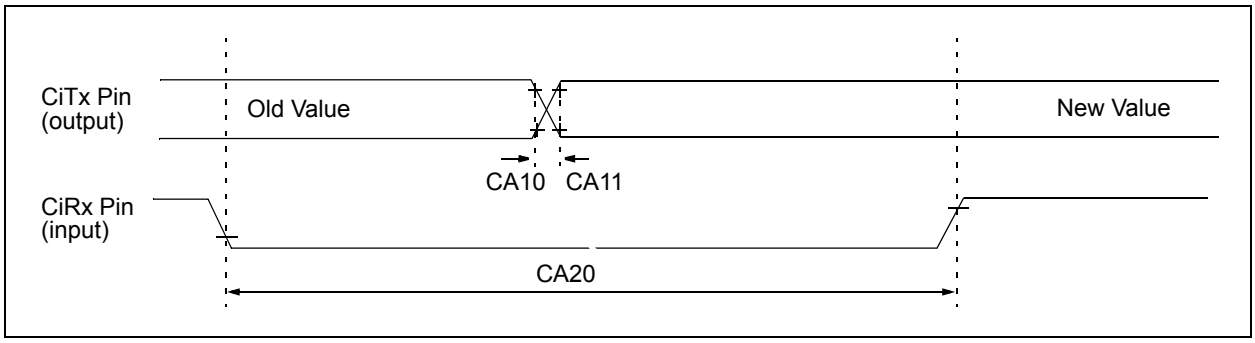


TABLE 28-38: ECAN™ MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
CA10	TioF	Port Output Fall Time	—	—	—	ns	See parameter D032
CA11	TioR	Port Output Rise Time	—	—	—	ns	See parameter D031
CA20	Tcwf	Pulse Width to Trigger CAN Wake-up Filter	120			ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

APPENDIX A: REVISION HISTORY

Revision A (September 2007)

Initial release of this document.

Revision B (March 2008)

This revision includes minor typographical and formatting changes throughout the data sheet text. In addition, redundant information was removed that is now available in the respective chapters of the *dsPIC33F/PIC24H Family Reference Manual*, which can be obtained from the Microchip web site (www.microchip.com).

The major changes are referenced by their respective section in the following table.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Note 1 added to all pin diagrams (see **"Pin Diagrams"**) Updated the **"PIC24HJ32GP302/304, PIC24HJ64GPX02/X04 and PIC24HJ128GPX02/X04 Controller Families"** table as follows: • PIC24HJ128GP804 changed to PIC24HJ128GP504 • PIC24HJ128GP804 changed to PIC24HJ128GP504 • Added new column: External Interrupts • Added Note 3
Section 1.0 "Device Overview"	Updated parameters PMA0, PMA1 and PMD0 through PMPD7 (Table 1-1)
Section 6.0 "Interrupt Controller"	IFS0-IFSO4 changed to IFSx (see **Section 6.3.2 "IFSx"**) IEC0-IEC4 changed to IECx (see **Section 6.3.3 "IECx"**) IPC0-IPC19 changed to IPCx (see **Section 6.3.4 "IPCx"**)
Section 7.0 "Direct Memory Access (DMA)"	Updated parameter PMP (see Table 7-1)
Section 8.0 "Oscillator Configuration"	Updated the third clock source item (External Clock) in **Section 8.1.1 "System Clock Sources"** Updated TUN<5:0> (OSCTUN<5:0>) bit description (see Register 8-4)
Section 19.0 "10-bit/12-bit Analog-to-Digital Converter (ADC1)"	Added Note 2 to Figure 19-3
Section 24.0 "Special Features"	Added Note 2 to Figure 24-1 Added Note after second paragraph in **Section 24.2 "On-Chip Voltage Regulator"**